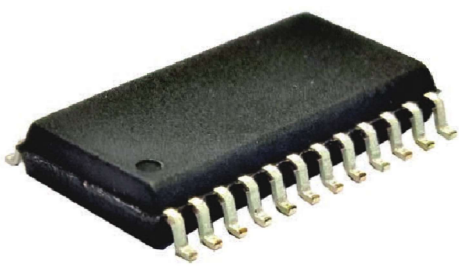



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	-	-	2.64
A1	0.10	0.15	0.20
A2	2.24	2.34	2.44
b	0.39	-	0.47
b1	0.38	0.41	0.43
c	0.25	-	0.30
c1	0.24	0.25	0.26
D	15.19	15.29	15.38
Df	15.29	-	15.79
E	10.10	10.30	10.50
E1	7.40	7.50	7.60
e	1.27BSC		
L	0.71	0.86	1.01
L1	1.30	1.40	1.50
θ	0	-	8°
f	0.05	-	0.20

Note:

1. All dimension are in mm.
2. Dim D & E1 does not include plastic flash;  
Df includes plastic flash(f);  
Flash: Plastic residual around body edge after dejunk/singulation.
3. Dim b does not include dambar protrusion/intrusion.
4. Plating thickness 0.007mm-0.020mm



拟制		复审	
审核		会签	
		标准化	
		批准	
制图		批准	
幅面: A4		比例: 1:1	

更改标记	更改内容	签名	日期
VKXHSOP24V11_POD 产品外形图名称		 永嘉微电 Vinka Microelectronics	
		单位	版本
		mm	V1.1
第 1 张		共 1 张	

⊕ - ▢